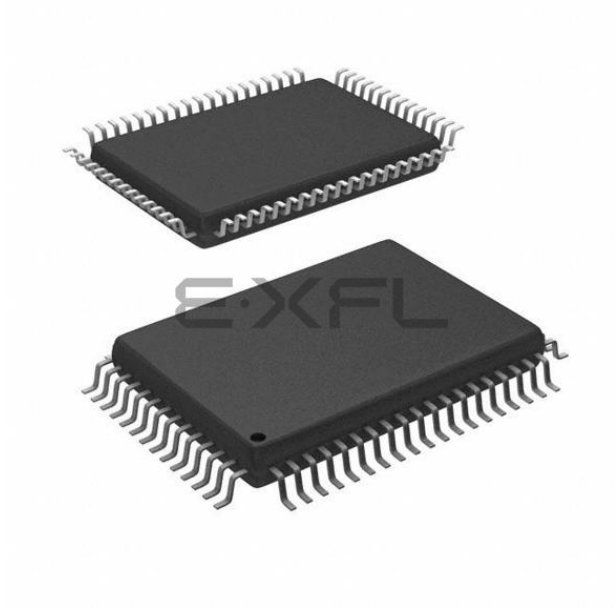


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	F²MC-8L
Core Size	8-Bit
Speed	10MHz
Connectivity	EBI/EMI, Serial I/O, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	53
Program Memory Size	16KB (16K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 6V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-BQFP
Supplier Device Package	64-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb89635rpf-g-1444

■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than V_{CC} or lower than V_{SS} is applied to input and output pins other than medium- and high-voltage pins or if higher than the voltage which shows on “1. Absolute Maximum Ratings” in section “■ Electrical Characteristics” is applied between V_{CC} and V_{SS}.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AV_{CC} and AVR) and analog input from exceeding the digital power supply (V_{CC}) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be AV_{CC} = DAVC = V_{CC} and AV_{SS} = AVR = V_{SS} even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although V_{CC} power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that V_{CC} ripple fluctuations (P-P value) will be less than 10% of the standard V_{CC} value at the commercial frequency (50 Hz to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

When an external clock is used, oscillation stabilization time is required even for power-on reset (option selection) and wake-up from stop mode.

■ PROGRAMMING TO THE EPROM ON THE MB89P637

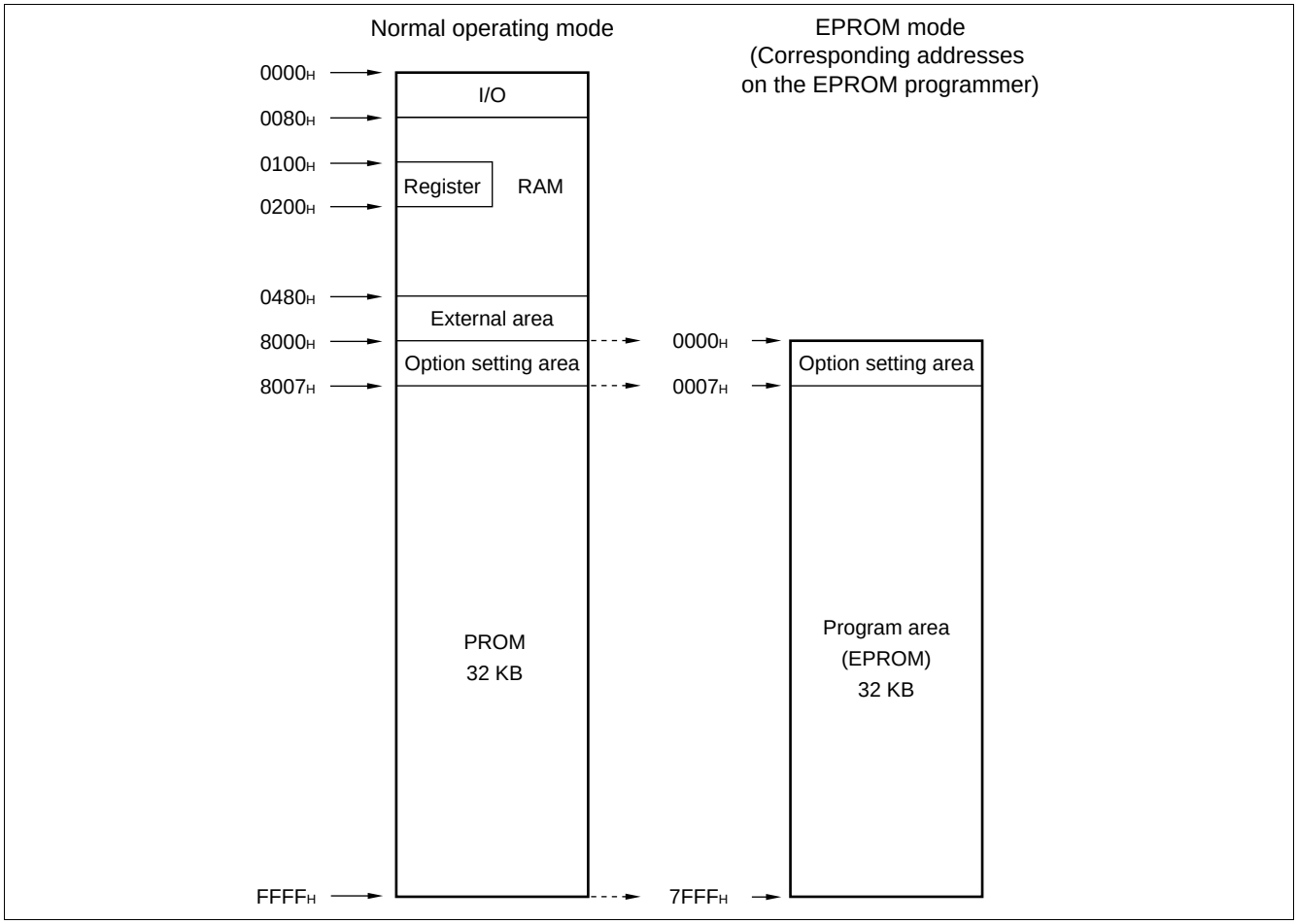
The MB89P637 is an OTPROM version of the MB89630 series.

1. Features

- 32-Kbytes PROM on chip
- Options can be set using the EPROM programmer.
- Equivalency to the MBM27C256A in EPROM mode (when programmed with the EPROM programmer)

2. Memory Space

Memory space in each mode is illustrated below.



3. Programming to the EPPROM

In EPROM mode, the MB89P637 functions equivalent to the MBM27C256A. This allows the PROM to be programmed with a general-purpose EPROM programmer by using the dedicated socket adapter.

However, the electronic signature mode cannot be used.

When the operating ROM area for a single chip is 32 Kbytes (8007_H to $FFFF_H$) the EPROM can be programmed as follows:

- **Programming procedure**

(1) Set the EPROM programmer to the MBM27C256A.

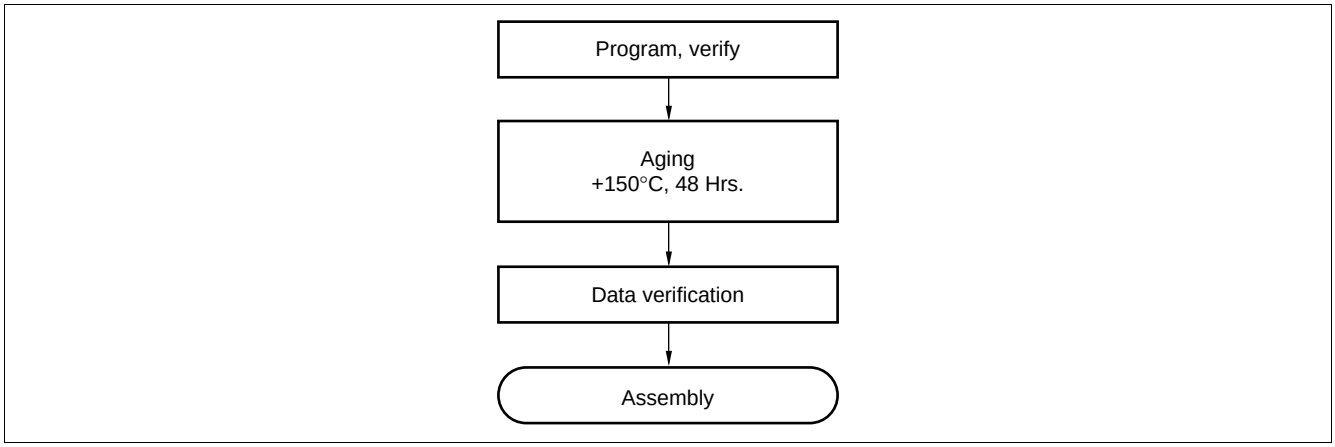
(2) Load program data into the EPROM programmer at 0007_H to $7FFF_H$. (Note that addresses 8000_H to $FFFF_H$ in the operating mode assign to 0000_H to $7FFF_H$ in EPROM mode).

(3) Load option data into addresses 0000_H to 0006_H of the EPROM programmer.
(For information about each corresponding option, see “8. OTPROM Option Bit Map”.)

(4) Program with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

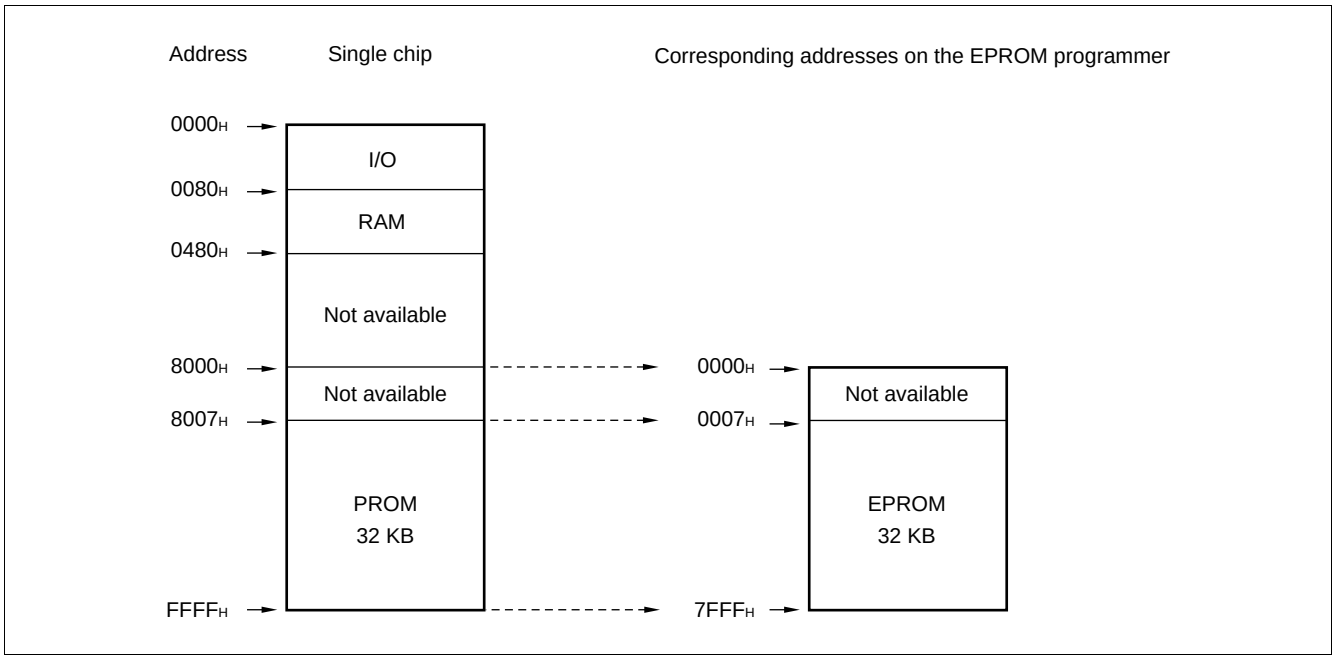
■ PROGRAMMING TO THE EPROM WITH PIGGYBACK/EVALUATION DEVICE

1. EPROM for Use

MBM27C256A-20CZ, MBM27C256A-20TV

2. Memory Space

Memory space in each mode, such as 32-Kbyte PROM, option area is diagrammed below.



3. Programming to the EPROM

(1) Set the EPROM programmer to the MBM27C256A.

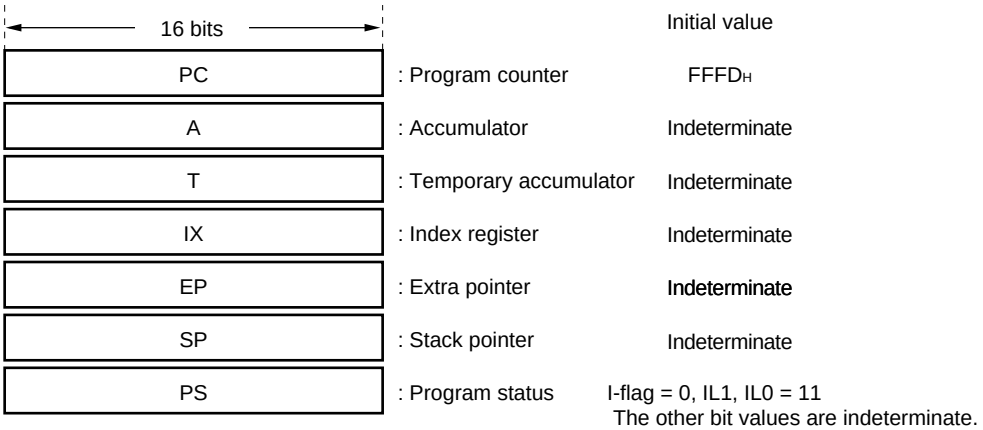
(2) Load program data into the EPROM programmer at 0007_H to $7FFF_H$.

(3) Program to 0000_H to $7FFF_H$ with the EPROM programmer.

2. Registers

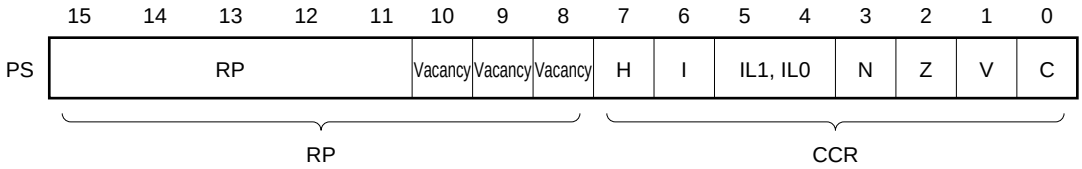
The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following dedicated registers are provided:

Program counter (PC):	A 16-bit register for indicating the instruction storage positions
Accumulator (A):	A 16-bit temporary register for storing arithmetic operations, etc. When the instruction is an 8-bit data processing instruction, the lower byte is used.
Temporary accumulator (T):	A16-bit register which performs arithmetic operations with the accumulator When the instruction is an 8-bit data processing instruction, the lower byte is used.
Index register (IX):	A16-bit register for index modification
Extra pointer (EP):	A16-bit pointer for indicating a memory address
Stack pointer (SP):	A16-bit register for indicating a stack area
Program status (PS):	A16-bit register for storing a register pointer, a condition code



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)

• Structure of the program status register

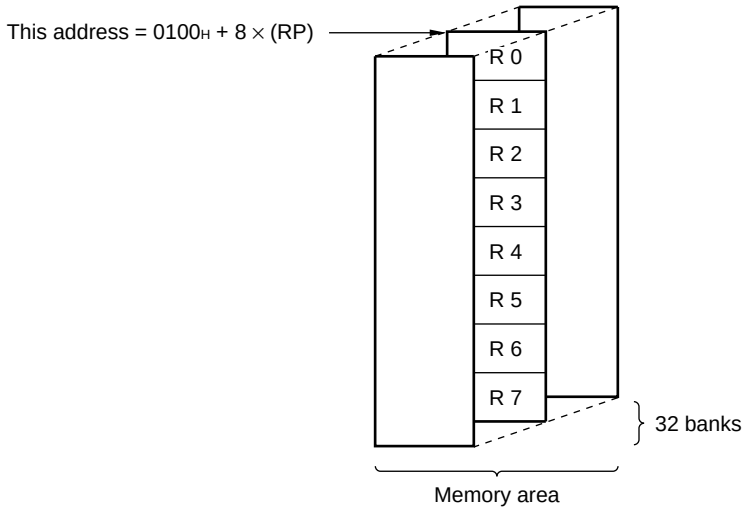


The following general-purpose registers are provided:

General-purpose registers: An 8-bit register for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers and up to a total of 32 banks can be used on the MB89630R series. The bank currently in use is indicated by the register bank pointer (RP).

• Register bank configuration



■ I/O MAP

Address	Read/write	Register name	Register description
00H	(R/W)	PDR0	Port 0 data register
01H	(W)	DDR0	Port 0 data direction register
02H	(R/W)	PDR1	Port 1 data register
03H	(W)	DDR1	Port 1 data direction register
04H	(R/W)	PDR2	Port 2 data register
05H	(W)	BCTR	External bus pin control register
06H	Vacancy		
07H	(R/W)	SYCC	System clock control register
08H	(R/W)	STBC	System clock control register
09H	(R/W)	WDTE	Watchdog timer control register
0AH	(R/W)	TBCR	Timebase timer control register
0BH	(R/W)	WPCR	Watch prescaler control register
0CH	(R/W)	CHG3	Port 3 switching register
0DH	(R/W)	PDR3	Port 3 data register
0EH	(W)	DDR3	Port 3 data direction register
0FH	(R/W)	PDR4	Port 4 data register
10H	(W)	DDR4	Port 4 data direction register
11H	(R/W)	BUZR	Buzzer register
12H	(R/W)	PDR5	Port 5 data register
13H	(R/W)	PDR6	Port 6 data register
14H	(R)	PDR7	Port 7 data register
15H	(R/W)	PCR1	PWC pulse width control register 1
16H	(R/W)	PCR2	PWC pulse width control register 2
17H	(R/W)	RLBR	PWC reload buffer register
18H	(R/W)	TMCR	16-bit timer control register
19H	(R/W)	TCHR	16-bit timer count register (H)
1AH	(R/W)	TCLR	16-bit timer count register (L)
1BH	Vacancy		
1CH	(R/W)	SMR1	Serial mode register
1DH	(R/W)	SDR1	Serial data register
1EH	Vacancy		
1FH	Vacancy		

(Continued)

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

($AV_{SS} = V_{SS} = 0.0$ V)

Parameter	Symbol	Value		Unit	Remarks
		Min.	Max.		
Power supply voltage	V_{CC}	$V_{SS} - 0.3$	$V_{SS} + 7.0$	V	*
	AV_{CC}	$V_{SS} - 0.3$	$V_{SS} + 7.0$	V	*
A/D converter reference input voltage	AVR	$V_{SS} - 0.3$	$V_{SS} + 7.0$	V	AVR must not exceed "AV_{CC} + 0.3 V".
Input voltage	V_I	$V_{SS} - 0.3$	$V_{CC} + 0.3$	V	Except P50 to P53
	V_{I2}	$V_{SS} - 0.3$	$V_{SS} + 7.0$	V	P50 to P53
Output voltage	V_O	$V_{SS} - 0.3$	$V_{CC} + 0.3$	V	Except P50 to P53
	V_{O2}	$V_{SS} - 0.3$	$V_{SS} + 7.0$	V	P50 to P53
"L" level maximum output current	I_{OL}	—	20	mA	
"L" level average output current	I_{OLAV}	—	4	mA	Average value (operating current × operating rate)
"L" level total maximum output current	ΣI_{OL}	—	100	mA	
"L" level total average output current	ΣI_{OLAV}	—	40	mA	Average value (operating current × operating rate)
"H" level maximum output current	I_{OH}	—	–20	mA	
"H" level average output current	I_{OHAV}	—	–4	mA	Average value (operating current × operating rate)
"H" level total maximum output current	ΣI_{OH}	—	–50	mA	
"H" level total average output current	ΣI_{OHAV}	—	–20	mA	Average value (operating current × operating rate)
Power consumption	P_D	—	500	mW	
Operating temperature	T_A	–40	+85	°C	
Storage temperature	Tstg	–55	+150	°C	

* : Use AV_{CC} and V_{CC} set at the same voltage.
Take care so that AV_{CC} does not exceed V_{CC}, such as when power is turned on.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

3. DC Characteristics

(AV_{CC} = V_{CC} = 5.0 V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
"H" level input voltage	V_{IH1}	P00 to P07, P10 to P17, P22, P23, P31, P34, P37, P41, P43, P51 to P53	—	0.7 V_{CC}	—	V_{CC} + 0.3	V	P51 to P53 with pull-up resistor
	V_{IH2}	P51 to P53		0.7 V_{CC}	—	V_{SS} + 6.0	V	Without pull-up resistor
	V_{IHS}	$\overline{RST}$, MOD0, MOD1, P30, P32, P33, P35, P36, P40, P42,P50, P72 to P74		0.8 V_{CC}	—	V_{CC} + 0.3	V	P50 with pull-up resistor
	V_{IHS2}	P50, P70, P71		0.8 V_{CC}	—	V_{SS} + 6.0	V	Without pull-up resistor
"L" level input voltage	V_{IL}	P00 to P07, P10 to P17, P22, P23, P31, P34, P37, P41, P43		V_{SS} – 0.3	—	0.3 V_{CC}	V	
	V_{ILS}	P30, P32, P33, P35, P36, P40, P42, P50 to P53, P70 to P74, $\overline{RST}$, MOD0, MOD1		V_{SS} – 0.3	—	0.2 V_{CC}	V	
Open-drain output pin application voltage	V_D	P50 to P53		V_{SS} – 0.3	—	V_{SS} + 6.0	V	
"H" level output voltage	V_{OH}	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P43	I_{OH} = –2.0 mA	4.0	—	—	V	
"L" level output voltage	V_{OL}	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P43, P50 to P53, P60 to P67, $\overline{RST}$	I_{OL} = 4.0 mA	—	—	0.4	V	
Input leakage current (Hi-z output leakage current)	I_{LI}	P00 to P07, P10 to P17, P20 to P23, P30 to P37, P40 to P43, P50 to P53, P70 to P74, MOD0, MOD1	0.0 V < V_I < V_{CC}	—	—	±5	µA	Without pull-up resistor

(Continued)

(AV_{CC} = V_{CC} = 5.0 V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
Pull-up resistance	R_{PULL}	P00 to P07, P10 to P17, P30 to P37, P40 to P43, P50 to P53, P72 to P74	V_I = 0.0 V	25	50	100	kΩ	With pull-up resistor
Power supply current*1	I_{CC1}	V_{CC}	F_{CH} = 10 MHz, V_{CC} = 5.0 V, t_{inst}*2 = 0.4 µs	—	12	20	mA	
	I_{CC2}		F_{CH} = 10 MHz, V_{CC} = 3.0 V, t_{inst}*2 = 6.4 µs	—	1.0	2	mA	MB89635R/ 636R/637R/ PV630
				—	1.5	2.5	mA	MB89P637
	I_{CCS1}		Sleep mode: F_{CH} = 10 MHz, V_{CC} = 5.0 V, t_{inst}*2 = 0.4 µs	—	3	7	mA	
	I_{CCS2}		Sleep mode: F_{CH} = 10 MHz, V_{CC} = 3.0 V, t_{inst}*2 = 6.4 µs	—	0.5	1.5	mA	
	I_{CCL}		F_{CL} = 32.768 kHz, V_{CC} = 3.0 V, Subclock mode	—	50	100	µA	MB89635R/ 636R/637R/ PV630
				—	500	700	µA	MB89P637
	I_{CCLS}		F_{CL} = 32.768 kHz, V_{CC} = 3.0 V, Subclock sleep mode	—	25	50	µA	
	I_{CCT}		F_{CL} = 32.768 kHz, V_{CC} = 3.0 V • Watch mode • Main clock stop mode at dual-clock system	—	3	15	µA	
	I_{CCH}		T_A = +25°C • Subclock stop mode • Main clock stop mode at single-clock system	—	—	1	µA	

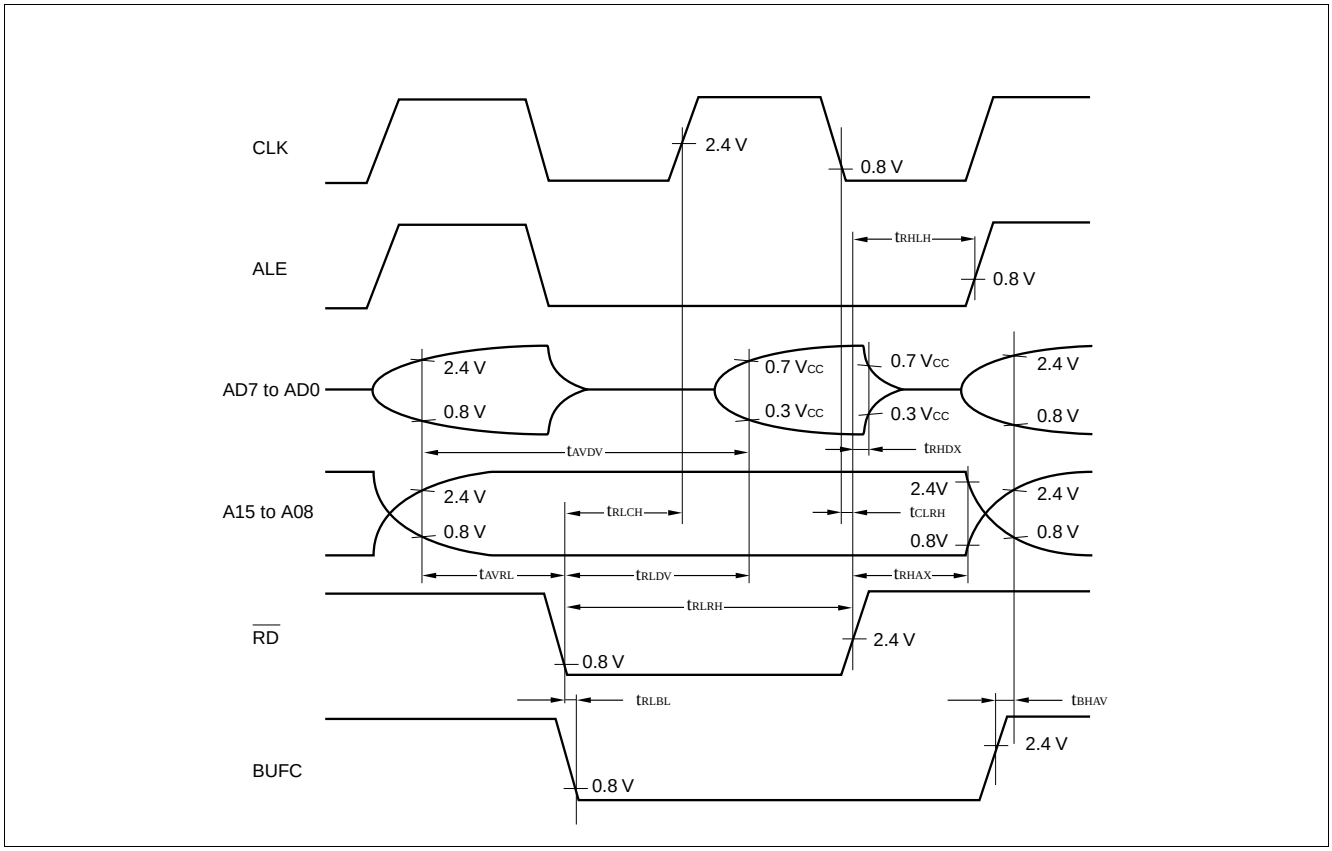
(Continued)

(6) Bus Read Timing

(V_{CC} = 5.0 V±10%, 10 MHz, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
				Min.	Max.		
Valid address → $\overline{RD}$ ↓ time	t_{AVRL}	$\overline{RD}$, A15 to A08, AD7 to AD0	—	1/4 t_{inst}*– 64 ns	—	µs	
$\overline{RD}$ pulse width	t_{RLRH}	$\overline{RD}$		1/2 t_{inst}*– 20 ns	—	µs	
Valid address → data read time	t_{AVDV}	AD7 to AD0, A15 to A08		1/2 t_{inst}*	200	µs	No wait
$\overline{RD}$ ↓ → data read time	t_{RLDV}	$\overline{RD}$, AD7 to AD0		1/2 t_{inst}*– 80 ns	120	µs	No wait
$\overline{RD}$ ↑ → data hold time	t_{RHDX}	AD7 to AD0, $\overline{RD}$		0	—	µs	
$\overline{RD}$ ↑ → ALE ↑ time	t_{RHLH}	$\overline{RD}$, ALE		1/4 t_{inst}*– 40 ns	—	µs	
$\overline{RD}$ ↑ → address loss time	t_{RHAX}	$\overline{RD}$, A15 to A08		1/4 t_{inst}*– 40 ns	—	µs	
$\overline{RD}$ ↓ → CLK ↑ time	t_{RLCH}	$\overline{RD}$, CLK		1/4 t_{inst}*– 40 ns	—	µs	
CLK ↓ → $\overline{RD}$ ↑ time	t_{CLRH}			0	—	ns	
$\overline{RD}$ ↓ → BUFC ↓ time	t_{RLBL}	$\overline{RD}$, BUFC		–5	—	µs	
BUFC ↑ → valid address time	t_{BHAV}	A15 to A08, AD7 to AD0, BUFC		5	—	µs	

* : For information on t_{inst}, see “(4) Instruction Cycle”.

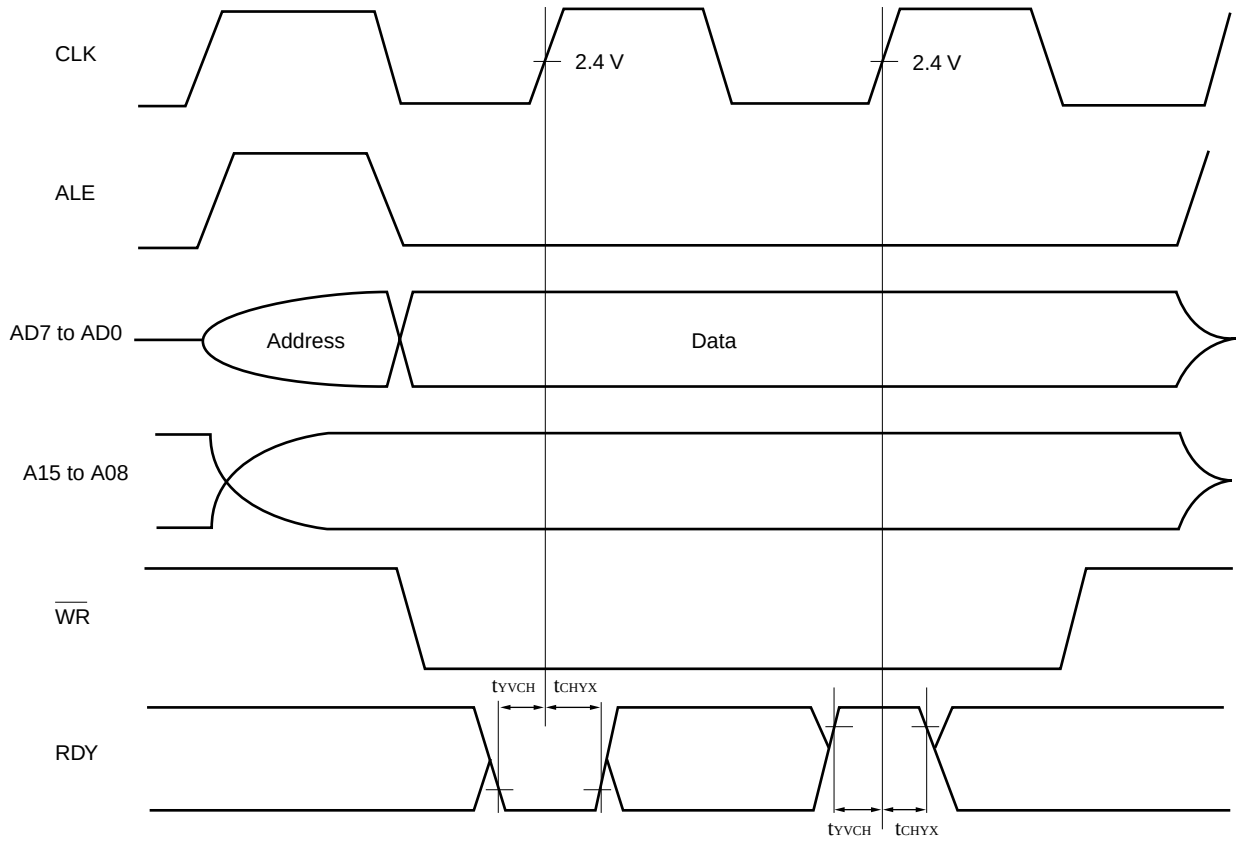


(8) Ready Input Timing

(V_{CC} = 5.0 V±10%, F_{CH} = 10 MHz, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

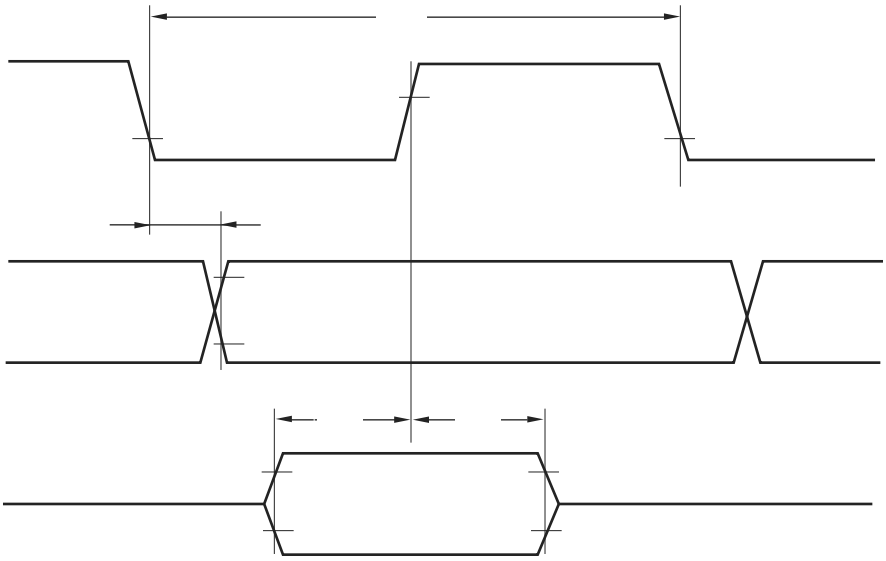
Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
				Min.	Max.		
RDY valid → CLK ↑ time	t_{YVCH}	RDY, CLK	—	60	—	ns	*
CLK ↑ → RDY loss time	t_{CHYX}			0	—	ns	*

* : This characteristics are also applicable to the read cycle.

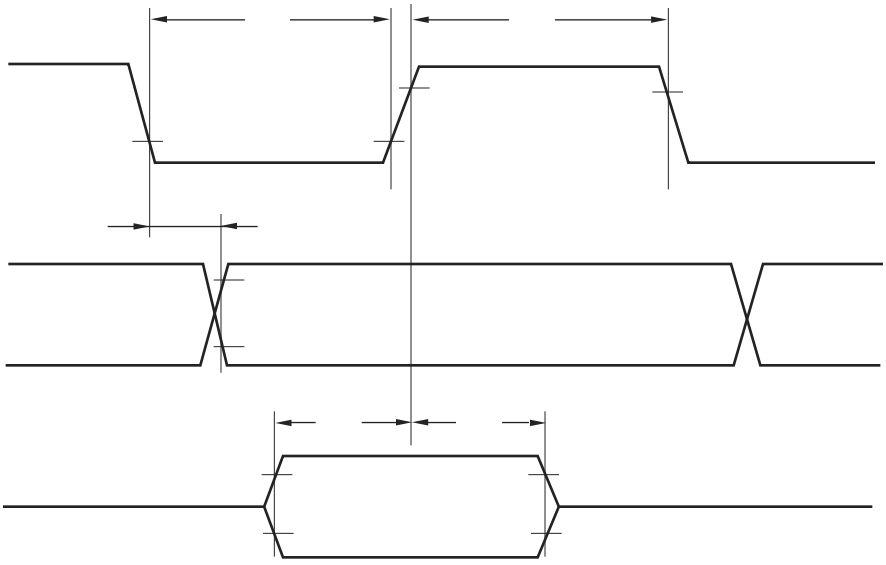


Note: The bus cycle is also extended in the read cycle in the same manner.

• **Internal shift clock mode**



• **External shift clock mode**

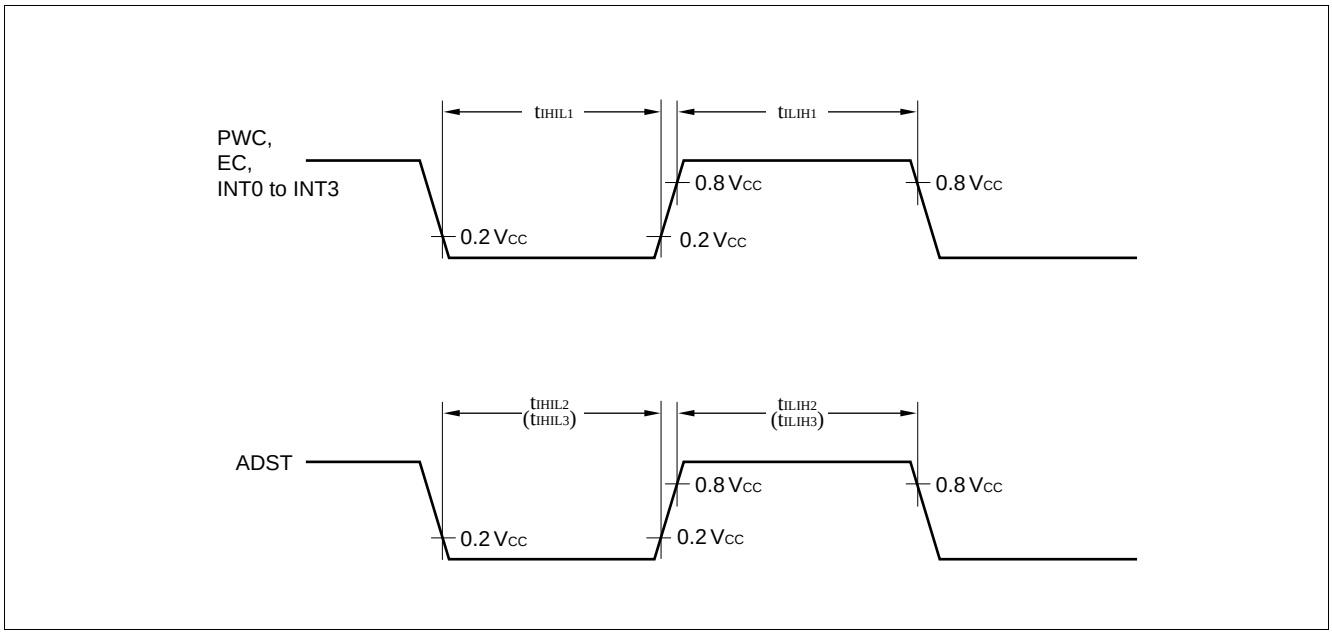


(10) Peripheral Input Timing

(V_{CC} = 5.0 V±10%, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin name	Value		Unit	Remarks
			Min.	Max.		
Peripheral input “H” pulse width 1	t_{ILIH1}	PWC, INT0 to INT3,EC	2 t_{inst}*	—	µs	
Peripheral input “L” pulse width 1	t_{IHIL1}		2 t_{inst}*	—	µs	
Peripheral input “H” pulse width 2	t_{ILIH2}	ADST	2^8 t_{inst}*	—	µs	A/D mode
Peripheral input “L” pulse width 2	t_{IHIL2}		2^8 t_{inst}*	—	µs	A/D mode
Peripheral input “H” pulse width 3	t_{ILIH3}	ADST	2^8 t_{inst}*	—	µs	Sense mode
Peripheral input “L” pulse width 3	t_{IHIL3}		2^8 t_{inst}*	—	µs	Sense mode

* : For information on t_{inst}, see “(4) Instruction Cycle”.



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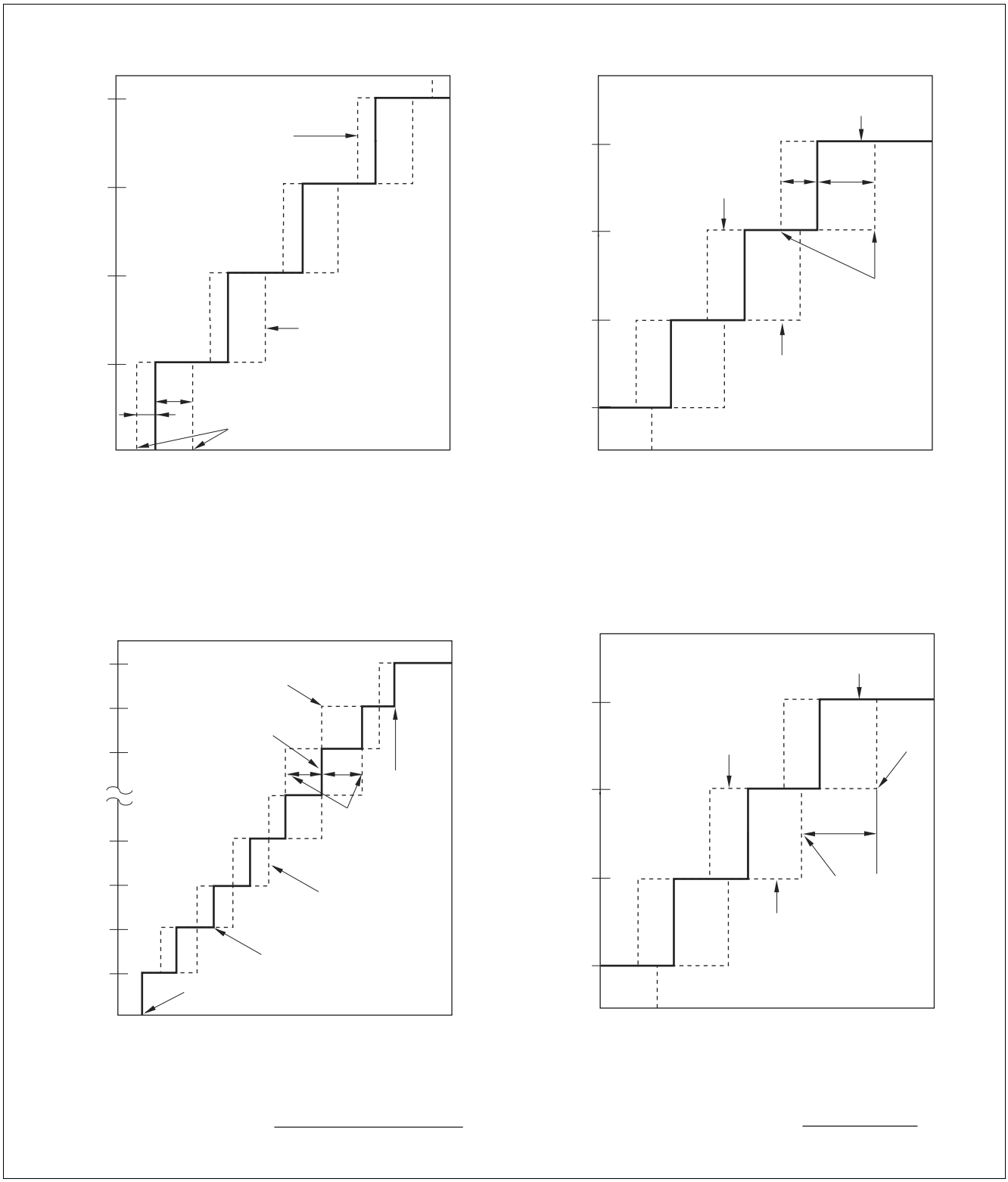
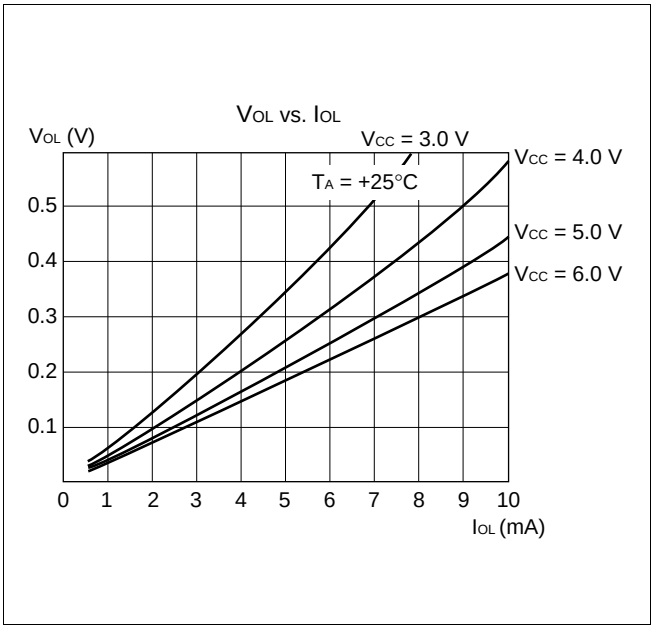
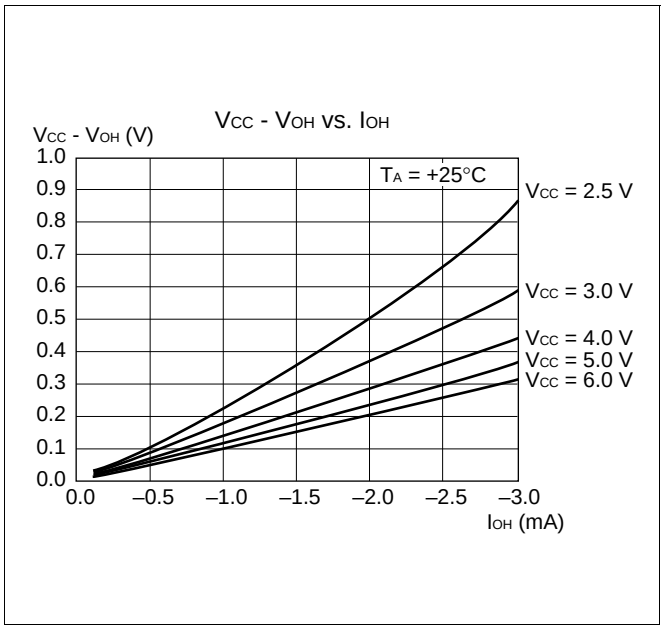


■ CHARACTERISTICS EXAMPLE

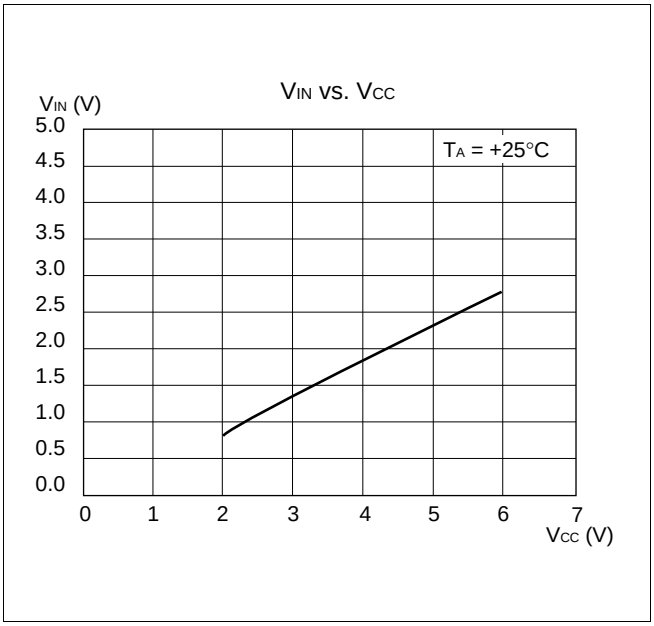
(1) “L” Level Output Voltage



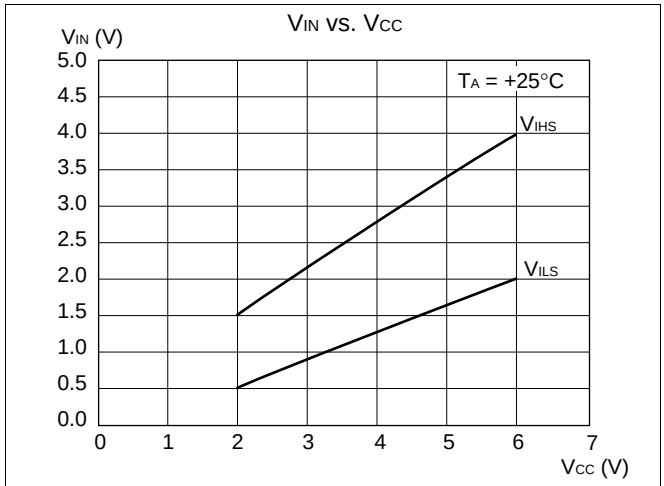
(2) “H” Level Output Voltage



(3) “H” Level Input Voltage/“L” Level Input Voltage (CMOS Input)



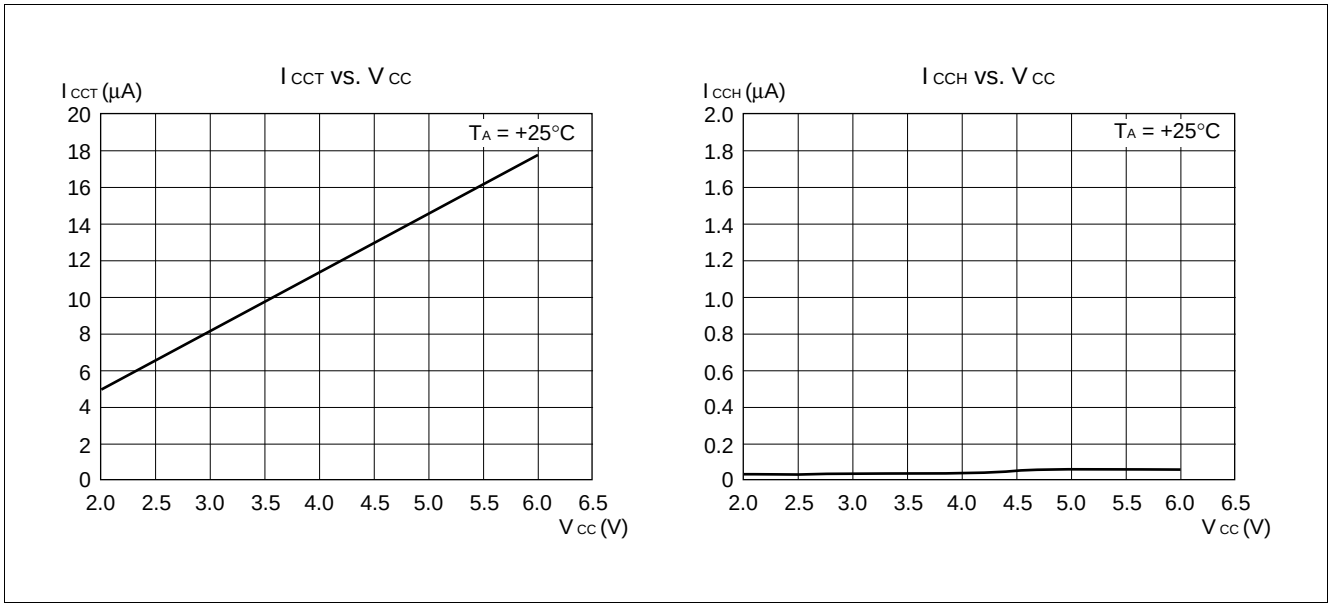
(4) “H” Level Input Voltage/“L” Level Input Voltage (Hysteresis Input)



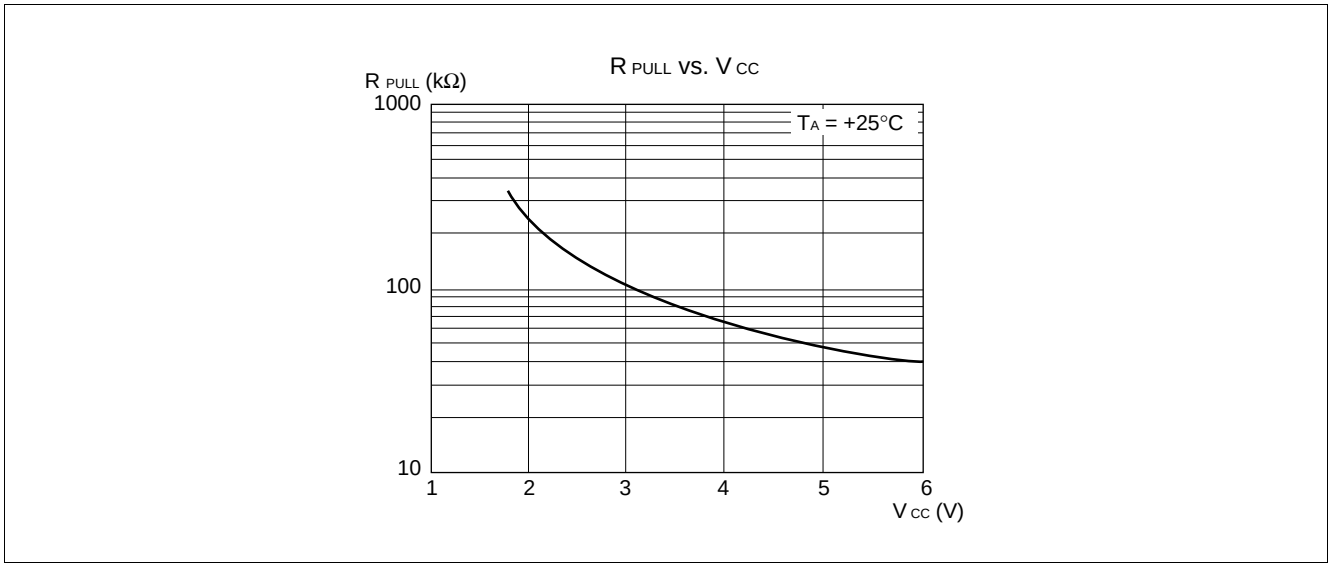
V_{IHS}: Threshold as the input voltage in hysteresis characteristics is set to “H” level

V_{ILS}: Threshold as the input voltage in hysteresis characteristics is set to “L” level

(Continued)



(6) Pull-up Resistance



■ ORDERING INFORMATION

Part number	Package	Remarks
MB89635RP-SH MB89636RP-SH MB89637RP-SH MB89P637P-SH	64-pin Plastic SH-DIP (DIP-64P-M01)	
MB89635RPF MB89636RPF MB89637RPF MB89P637PF	64-pin Plastic QFP (FPT-64P-M06)	
MB89635RPMC MB89636RPMC MB89637RPMC	64-pin Plastic QFP (FPT-64P-M23)	
MB89PV630-101CF MB89PV630-102CF	64-pin Ceramic MQFP (MQP-64C-P01)	
MB89PV630-101C MB89PV630-102C	64-pin Ceramic MDIP (MDP-64C-P02)	

MEMO

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